

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10677092
<b>Filing Date:</b>	30-Sep-2003
<b>Title of Invention:</b>	INCREASING THERMAL CONDUCTIVITY OF HOST POLYMER USED WITH LASER ENGRAVING METHODS AND COMPOSITIONS
<b>First Named Inventor/Applicant Name:</b>	Brian Labrec
<b>Filer:</b>	Joel R. Meyer
<b>Attorney Docket Number:</b>	P0889D

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>300</b>